Product / Package Information

Package	SOIC_IC
Body Size	300 mils
Lead Count	20
Terminal Finish	100 Sn
MS Number	MS010781C

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.22 E-01	87.7	877000	64.35	643497
Thermosets	Epoxy Resin	Proprietary	2.40 E-02	5.0	50000	3.67	36687
Thermosets	Phenol Resin	Proprietary	2.40 E-02	5.0	50000	3.67	36687
Thermosets	Epoxy Cresol Novolac	29690-82-2	9.62 E-03	2.0	20000	1.47	14675
Other inorganic materials	Carbon Black	1333-86-3	1.44 E-03	0.3	3000	0.22	2201
Subtotal			4.81 E-01	100	1000000	73.37	733748

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.52 E-01	97.5	975000	23.14	231404
Copper & its alloys	Iron	7439-89-6	3.65 E-03	2.35	23500	0.56	5577
Copper & its alloys	Zinc	7440-66-6	1.87 E-04	0.12	1200	0.03	285
Copper & its alloys	Phosphorus	7723-14-0	4.67 E-05	0.03	300	0.01	71
Subtotal			1.56 E-01	100.00	1000000	23.73	237337

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.57 E-03	100.0	1000000	0.24	2397

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	6.64 E-03	100.0	1000000	1.01	10128

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	7.40 E-04	99.99	1000000	0.11	1129

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	8.88 E-03	100.0	1000000	1.36	13552

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	8.96 E-04	80	800000	0.14	1367
Thermosets	Epoxy Resin	Proprietary	1.68 E-04	15	150000	0.03	256
Others	Curing agent & hardener	Proprietary	5.60 E-05	5	50000	0.01	85
Subtotal			1.12 E-03	100	1000000	0.17	1709

	Weight (g)	Percentage (%)	PPM
Package Totals	**6.55 E-01**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES